



Product Information

SC9-TOCCATA • CompactPCI® Serial CPU Card

11th Generation Intel® Core™ & XEON® W Processors
Tiger Lake H



General

The SC9-TOCCATA is a rich featured high performance 4HP/3U CompactPCI® Serial CPU board, equipped with an Intel® 11th Generation XEON® Processor (Tiger Lake H45 platform) for demanding industrial applications.

The SC9-TOCCATA front panel is provided with three 2.5Gbps Ethernet jacks for networking (2 x TCC/TSN capable) and three 10Gbps USB Type-C receptacles (DisplayPort Alternate Mode enabled) for versatile device and display attachment.

On-board mass-storage solutions are based on low profile mezzanine expansion cards, which accommodate up to two M.2 style SSD modules. One of the M.2 sockets is suitable for a fast NVMe (PCI Express® Gen4 x 4) module.

The SC9-TOCCATA is equipped with up to 64GB DDR4 ECC RAM. Up to 32GB memory-down are provided for rugged applications, and another 32GB are available via the DDR4 ECC SODIMM socket.

The 11th Generation XEON® and Core™ processors are accompanied by the RM590E mobile PCH, for a maximum of high speed I/O resources (e.g. PCI Express®, SATA, USB). Altogether with the processor, 25 PCIe® lanes in total are provided for backplane use, and another 8 lanes for local mezzanine expansion up to PCIe® Gen4 speed.

As an option, up to eight additional Gigabit Ethernet ports (either switch or NICs) are available via the backplane connector P6 by means of a mezzanine module.



Feature Summary

General

- ▶ PICMG® CompactPCI® Serial (CPCI-S.0) CPU card
- ▶ Form factor single size Eurocard (board dimensions 100x160mm²)
- ▶ Mounting height 3U
- ▶ Front panel width 4HP (8HP/12HP assembly with optional mezzanine side card)
- ▶ Front panel I/O connectors for typical system configuration (3 x 10Gbps USB Type-C DP Alt Mode, 3 x 2.5Gbps Ethernet RJ45)
- ▶ Backplane communication via PCI Express® up to Gen4, SATA 6G, USB 3.2, Gigabit Ethernet
- ▶ New AirMax VSe® backplane connectors up to 25Gb/s differential pair
- ▶ Local mezzanine expansion option, COTS and custom specific boards

Feature Summary

Processor Characteristics

- ▶ Intel® 11th Generation Mobile XEON® W or Core™ processor
- ▶ Tiger Lake H45 platform
- ▶ Up to 8-core, up to 3MB cache per core
- ▶ DDR4 3200 ECC RAM
- ▶ Gen 12 graphics, 4 displays up to 8k60
- ▶ TCC/TSN
- ▶ Extended temperature operation (CPU junction temperature range T_j up to -40°C to $+100^{\circ}\text{C}$)
- ▶ Embedded & industrial use conditions
- ▶ 45/35W configurable TDP, 25W TDP
- ▶ BGA soldered for optimum reliability
- ▶ Mobile Intel® Series 500 PCH (RM590E IOTG)

- ▶ Intel® Xeon® W processors (Industrial Use Case *)
- ▶ Up to 8 cores, 24MB cache, 32EU, Intel® vPro™ eligible
- ▶ W-11865MRE | 8c 24M | 4.7GHz Turbo | 2.6GHz Base | 45/35W | 32EU 1350MHz | ECC | TCC/TSN | VPro | T_j -40°C to $+100^{\circ}\text{C}$ | SC9-650D-TOCCATA
- ▶ W-11555MRE | 6c 12M | 4.5GHz Turbo | 2.6GHz Base | 45/35W | 32EU 1350MHz | ECC | TCC/TSN | VPro | T_j -40°C to $+100^{\circ}\text{C}$
- ▶ W-11155MRE | 4c 8M | 4.4GHz Turbo | 2.4GHz Base | 45/35W | 16EU 1250MHz | ECC | TCC/TSN | T_j -40°C to $+100^{\circ}\text{C}$
- ▶ W-11865MLE | 8c 24M | 4.5GHz Turbo | 1.5GHz Base | 25W | 32EU 1350MHz | ECC | TCC/TSN | VPro | T_j 0°C to $+100^{\circ}\text{C}$ | SC9-440D-TOCCATA
- ▶ W-11555MLE | 6c 12M | 4.4GHz Turbo | 1.9GHz Base | 25W | 32EU 1350MHz | ECC | TCC/TSN | VPro | T_j 0°C to $+100^{\circ}\text{C}$
- ▶ W-11155MLE | 4c 8M | 3.1GHz Turbo | 1.8GHz Base | 25W | 16EU 1250MHz | ECC | TCC/TSN | T_j 0°C to $+100^{\circ}\text{C}$ | SC9-340D-TOCCATA
- ▶ * disable core/graphics turbo for industrial use condition

- ▶ Intel® Core™ processors (Embedded Use Case)
- ▶ i7-11850HE | 8c 24M | 4.7GHz Turbo | 2.6GHz Base | 45/35W | 32EU 1350MHz | VPro | T_j 0°C to $+100^{\circ}\text{C}$
- ▶ i5-11500HE | 6c 12M | 4.5GHz Turbo | 2.6GHz Base | 45/35W | 32EU 1350MHz | VPro | T_j 0°C to $+100^{\circ}\text{C}$
- ▶ i3-11100HE | 4c 8M | 4.4GHz Turbo | 2.4GHz Base | 45/35W | 16EU 1250MHz | T_j 0°C to $+100^{\circ}\text{C}$
- ▶ 6600HE | 2c 8M | 2.6GHz | 35W | 16EU 1100MHz | T_j 0°C to $+100^{\circ}\text{C}$ | SC9-140D-TOCCATA
- ▶ 6600HLE | 2c 8M | 2.1GHz | 25W | 16EU 1100MHz | T_j 0°C to $+100^{\circ}\text{C}$

Feature Summary

AI (Artificial Intelligence) Resources

- ▶ DL Boost - set of instructions to accelerate AI workloads
- ▶ AVX512 - Advanced Vector Extensions & VNNI - Vector Neural Network Instructions - X86 instruction set which is designed to accelerate convolutional neural network for INT8 inference, helps accelerate workloads like image recognition
- ▶ GNA - Gaussian & Neural Accelerator - a low-power neural coprocessor for continuous inference at the edge, designated for offloading workloads including but not limited to noise reduction or speech recognition, saves power and frees CPU resources
- ▶ Intel® OpenVINO™ (Open Visual Inference and Neural network Optimization) toolkit 2022 - deploy high-performance, deep learning inference
- ▶ Intel® Edge Software Hub - edge computation software and packages
- ▶ Intel® DevCloud for the Edge - allows you to actively prototype and experiment with AI workloads for computer vision

Firmware

- ▶ Phoenix® UEFI (Unified Extensible Firmware Interface) V2.7
- ▶ Phoenix SCT (SecureCore Technology) Release V4.3.0
- ▶ ACPI V6.1
- ▶ Fully customizable by EKF
- ▶ Secure Boot and Measured Boot supported - meeting all demands as specified by Microsoft®
- ▶ Windows®, Linux and other (RT)OS supported
- ▶ Intel® AMT vPro® supported (disabled by default, must be enabled via BIOS setup)

Main Memory

- ▶ Integrated memory controller up to 64GB DDR4 3200 with hardware ECC *
 - ▶ DDR4 +ECC soldered memory up to 32GB (ultra rugged basic memory)
 - ▶ DDR4 +ECC SO-DIMM memory module socket up to 32GB (memory expansion option)
 - ▶ Total memory encryption
- * ECC with XEON® processor SKUs (industrial use)

Feature Summary

Graphics

- ▶ Integrated X^e Gen 12 graphics engine, 4 displays
- ▶ Up to 32EU
- ▶ Codec support HEVC/SCC/VP9/AV1
- ▶ HDR support power optimized
- ▶ Decode up to 8k60:
 - ▶ 2x 4k60 8b 4:2:0 AVC
 - ▶ 5k60 12b 4:2:2/4:4:4 HEVC/VP9/SCC
 - ▶ 8k60 12b 4:2:0 HEVC/VP9/SCC
 - ▶ 4k60 10b 4:2:0 AV1
- ▶ Encode up to 8k30:
 - ▶ 2x 4k60 8b 4:2:0 AVC
 - ▶ 5k60 10b 4:4:4 HEVC/VP9/SCC
 - ▶ 8k30 10b 4:2:0 HEVC/VP9/SCC
 - ▶ 2x 4k HEVC encode speed
- ▶ Up to 4 displays supported:
 - ▶ 1 Display: 8k60 HDR
 - ▶ 2 Displays: 8k60 SDR or 4k120 HDR + 5k120 HDR
 - ▶ 3 Displays: 4k60 HDR
 - ▶ 4 Displays: 4k60 HDR
- ▶ DisplayPort DP1.4a HBR3
- ▶ Multi-Stream Transport (MST) - display daisy chaining
- ▶ Integrated DP Alt Mode MUX
- ▶ Integrated audio

- ▶ Display front panel options:
 - ▶ 3 x Type-C connectors for either DisplayPort and USB usage
 - ▶ 4th DisplayPort optional via Type-C connector on low profile mezzanine card S40 or S48

Feature Summary

Networking

- ▶ Up to 11 Ethernet networking interfaces in total
- ▶ 3 x Front 2.5GBASE-T RJ45 - 3 x Intel® I226-IT NIC
- ▶ 2.5GBASE-T, 1000BASE-T, 100BASE-TX, 10BASE-T connections
- ▶ RJ45 Front port 1 - Intel® I226-IT, Intel® vPro®/AMT (Wake on LAN)
- ▶ RJ45 Front port 2 - Intel® I226-IT, TCC/TSN capable, PPS/PPM
- ▶ RJ45 Front port 3 - Intel® I226-IT, TCC/TSN capable
- ▶ Integrated TCC/TSN controller for front ports 2 & 3 (RM590E PCH) - Real Time networking
- ▶ TSN Precision time protocol (Time-Sensitive-Networking) as required e.g. for OPC UA and OpenAvnu
- ▶ Enables ultra-reliable low-latency communication (URLLC)
- ▶ Intel® Time Coordinated Computing (Intel® TCC) for time synchronisation and timeliness
- ▶ Option 8 x 1000BASE-T backplane w. S80-P6 mezzanine module - Marvell® Peridot switch
- ▶ Option 4 x 1000BASE-T backplane w. S82-P6 mezzanine module - 4 x Intel® I210-IT NIC
- ▶ Option 4 x 2.5GBASE-T backplane w. S83-P6 mezzanine module - 4 x Intel® I226-IT NIC
- ▶ Option 4 x 2.5GBASE-T RJ45 front w. SCJ-VEENA side card - 4 x Intel® I226-IT NIC (8HP assembly)
- ▶ Option 4 x 1000BASE-T M12-X front w. SCL-RHYTHM side card - 4 x Intel® I210-IT NIC (8HP assembly)
- ▶ Option RJ45 port 1 jack (vPro®/AMT) replacement by M12-X connector w. S02-M12 mezzanine (8HP)

Security

- ▶ Total memory encryption - hardware based
- ▶ ROP attack prevention - hardware based protection against browser malware attacks
- ▶ Advanced Crypto Key protection - hardware based
- ▶ Trusted Platform Module SLM9670
- ▶ TPM 2.0 for highest level of certified platform protection
- ▶ Infineon Optiga™ cryptographic processor
- ▶ Conforming to TCG 2.0 specification

Front Panel I/O (4HP)

- ▶ 3 x 2.5Gbps Ethernet RJ45 receptacles
- ▶ 2.5GBASE-T, 1000BASE-T, 100BASE-TX, 10BASE-Te
- ▶ Intel® vPro®/AMT supported (port 1 RJ45 connector - must be enabled via BIOS settings)
- ▶ Port 2 & 3 TCC/TSN enabled
- ▶ 3 x 10Gbps USB Type-C receptacles DisplayPort Alt Mode
- ▶ USB and/or DisplayPort usage
- ▶ USB 3.2 Gen 2x1 (formerly USB 3.1 Gen2) SuperSpeed+ 10Gbps
- ▶ USB-PD downstream facing ports 5V/3A (Infineon CYPD5225 EZ-PD™ CCG5 controller)
- ▶ DisplayPort 1.4
- ▶ Additional Type-C front I/O with low profile mezzanine e.g. S40 or S48

Feature Summary

Front Panel I/O (8/12HP)

- ▶ Variety of side cards available, common front panel 8HP/12HP with CPU card
- ▶ For backplanes with system slot right aligned
- ▶ Various I/O ports e.g. UART, Audio, RJ45 Ethernet, M12-X Ethernet, Wireless (SMA)
- ▶ Custom specific front panel and side card design

CompactPCI® Serial Backplane Resources

- ▶ PICMG® CPCI-5.0 CPU card & system slot controller
- ▶ 16 x PCIe Gen4 ¹ up to 16GT/s (2 links x8 for two fat pipe slots, derived directly from the Xeon® or Core™ CPU)
- ▶ 9 x PCIe Gen3 up to 8GT/s (1 link x4, 5 links x1 for peripheral slots, derived from the PCH)
- ▶ 5 x SATA 6G (from the PCH)
- ▶ 8 x USB3 ² (from the PCH)
- ▶ Option 8 x Gigabit Ethernet Marvell 88E6390 switch (S80-P6 low profile mezzanine expansion card)
- ▶ Option 4 x Gigabit Ethernet Intel® I210-IT NIC (S82-P6 low profile mezzanine expansion card)
- ▶ Option 4 x 2.5Gigabit Ethernet Intel® I226-IT NIC (S83-P6 low profile mezzanine expansion card)

- ▶ New backplane connectors AirMax VSe® up to 25Gbps per differential pair according to CompactPCI® Serial R3.0 (backward compatible to backplanes with AirMax VS® 12.5Gbps)
- ▶ 4HP CPU card front panel width when the adjacent board to the right is equipped with legacy AirMax VS® connectors (e.g. peripheral cards according to the CompactPCI® Serial R2.0 connector specification)
- ▶ 5HP CPU card front panel width and backplane slot pitch according to CompactPCI® Serial R4.0 when the adjacent board to the right is also equipped with the new AirMax VSe® connectors (e.g. multi CPU card system)

¹ The CPU is PCIe® Gen4 capable on these links (specified with CompactPCI® Serial R3.0)

² USB 3.2 Gen 2x1 SuperSpeed+ 10Gbps

Feature Summary

Local Expansion & Mezzanine Mass Storage Options

- ▶ Mezzanine side card connectors for optional local expansion
- ▶ Low profile mezzanine modules available (4HP front panel)
- ▶ Side cards available (8HP F/P assembly)
- ▶ HSE1 - PCIe Gen4 x4, 1 x USB3 10Gbps & 2 x USB2
- ▶ HSE2 - PCIe Gen3 x4 (configurable also 2x2, 4x1), 4th DisplayPort
- ▶ EXP - Legacy interface (eSPI, Audio, UART, I2C, GPIO)

- ▶ 4HP Low profile mezzanine module preferred options:
- ▶ S20-NVME Mezzanine module - M.2 2280 NVME SSD socket, 1 x Type-C USB F/P connector
- ▶ S40-NVME Mezzanine module - 1 x M.2 2280 NVME SSD socket, 1 x M.2 2280 SATA SSD socket, 2 x Type-C USB F/P connectors (1 connector enabled for DisplayPort alternate mode)
- ▶ S42-MC Mezzanine module - M.2 2280 NVME SSD socket, 2 x PCIe® Mini Card sockets
- ▶ S48-SSD Mezzanine module - 1 x M.2 2280 PCIe® x4 Gen4 SSD socket, 1 x M.2 2280 PCIe® x4 Gen3 SSD socket, Type-C USB F/P connector (enabled for DisplayPort alternate mode - 4th display)
- ▶ S80-P6 Mezzanine module - M.2 2280 NVMe SSD socket, 8 x Gigabit Ethernet via P6 backplane connector (switch based solution)
- ▶ S82-P6 Mezzanine module - M.2 NVMe SSD socket, 4 x GbE NIC via P6 backplane connector
- ▶ S83-P6 Mezzanine module - M.2 NVMe SSD socket, 4 x 2.5GbE NIC via P6 backplane connector
- ▶ Custom specific storage & I/O module design

- ▶ 8HP Mezzanine side card options:
- ▶ SCJ-VEENA Short side card - M.2 2280 NVMe SSD socket, 4 x 2.5GbE NIC, front panel RJ45, USB3
- ▶ SCL-RHYTHM Short side card - M.2 2280 NVMe SSD socket, 4 x GbE NIC, front panel M12-X
- ▶ SCZ-NVM - M.2 22110 NVMe SSD socket, quad UART, DisplayPort & USB3 connectors
- ▶ S02-M12 - RJ45 port 1 (vPro®/AMT) replacement by M12-X connector (top or bottom mount)
- ▶ Custom specific side card design - I/O and storage

- ▶ Backplane Coupler:
- ▶ SCX-PCIE - M.2 2280 NVMe/SATA SSD socket, PCIe® Mini Card socket, 3 x USB3, 3 x GbE RJ45 connectors, coupler for secondary CompactPCI® Serial backplane
- ▶ ECX-PCIE - Front I/O same as SCX, coupler for CompactPCI® Express secondary backplane

RT OS Board Support Packages

- ▶ Available on request

Applications

- ▶ High performance industrial and embedded computing, for x86 based software
- ▶ Automation, process control, test systems, demanding applications
- ▶ Edge computing, AI deep learning

Feature Summary

Environmental & Regulatory

- ▶ Suitable e.g. for industrial, transportation & instrumentation applications
- ▶ Designed & manufactured in Germany
- ▶ ISO 9001 certified quality management
- ▶ Long term availability
- ▶ Rugged solution
- ▶ Coating, sealing, underfilling on request
- ▶ Lifetime application support
- ▶ RoHS compliant
- ▶ Operating temperature 0°C to +70°C
- ▶ Operating temperature -40°C to +85°C (industrial temperature range) on request
- ▶ Storage temperature -40°C to +85°C, max. gradient 5°C/min
- ▶ Humidity 5% ... 95% RH non condensing
- ▶ Altitude -300m ... +3000m
- ▶ Shock 15g 0.33ms, 6g 6ms
- ▶ Vibration 1g 5-2000Hz
- ▶ MTBF 20.2 years (MIL-HDBK-217F, SN29500 @+40°C)
- ▶ EC Regulatory EN55035, EN55032, EN62368-1 (CE)

all items may be subject to technical changes w/o further notice

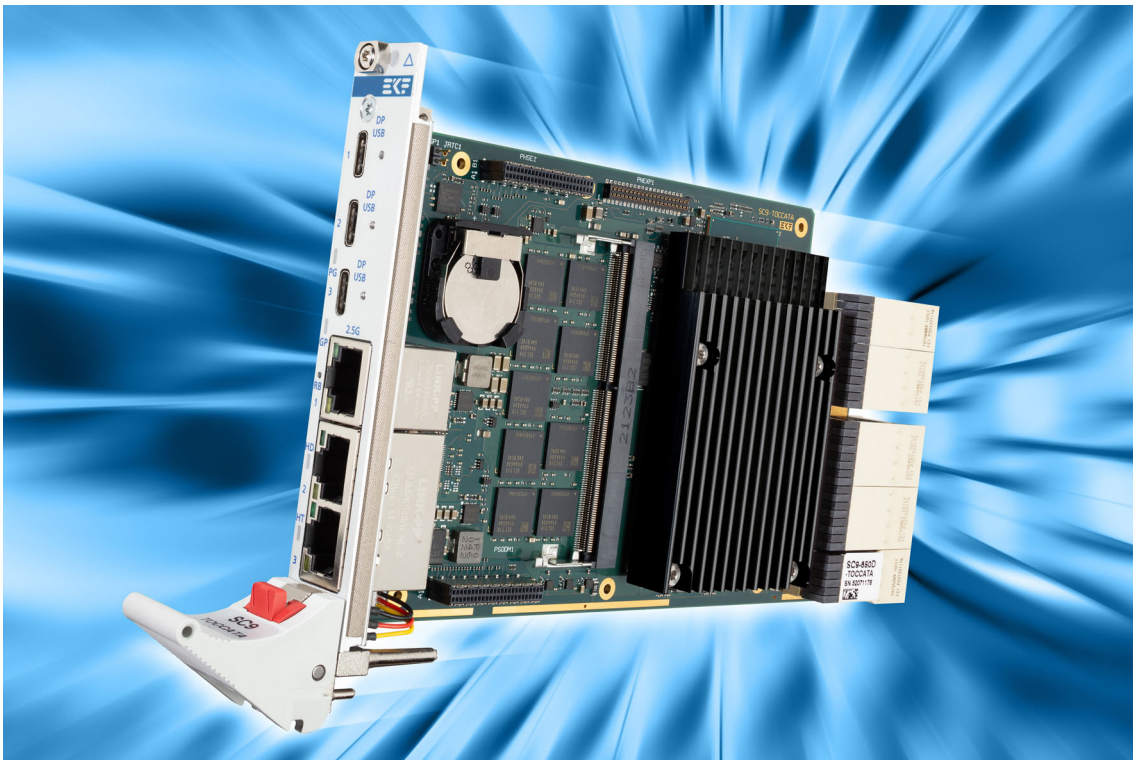


CompactPCI® Serial

While mechanically compliant to CompactPCI® Classic, CompactPCI® Serial (PICMG® CPCIS.0) defines a completely new card slot, based on PCI Express®, SATA, Gigabit Ethernet and USB serial data lines. Up to 6 high-speed backplane connectors P1 - P6 are provided on a system slot controller such as the SC9-TOCCATA, which can be considered as a root hub with respect to most signal lines. A passive backplane is used for distribution of a defined subset of I/O channels from the system slot to each of up to eight peripheral slots in a CompactPCI® Serial system.

Most CompactPCI® Serial peripheral slot cards require only the backplane connector P1, which comprises PCIe®, SATA and USB signals, resulting in a concise and inexpensive peripheral board design. More powerful peripheral cards profit from two so called Fat Pipe slots (PCIe® x 8).

The SC9-TOCCATA is a native CompactPCI® Serial CPU card, suitable for usage in a pure CPCI Serial environment. Due to its generous backplane capabilities (25 x PCI Express® up to Gen4, 8 x USB3, 5 x SATA 6G, up to 8 x GbE), very powerful industrial systems can be built.



Local Expansion

The SC9-TOCCATA is equipped with a set of high-speed local expansion interface connectors, which can be optionally used to attach either a low profile mezzanine module (fits into the 4HP front panel envelope) or a side card for an 8HP or even 12HP assembly in total.

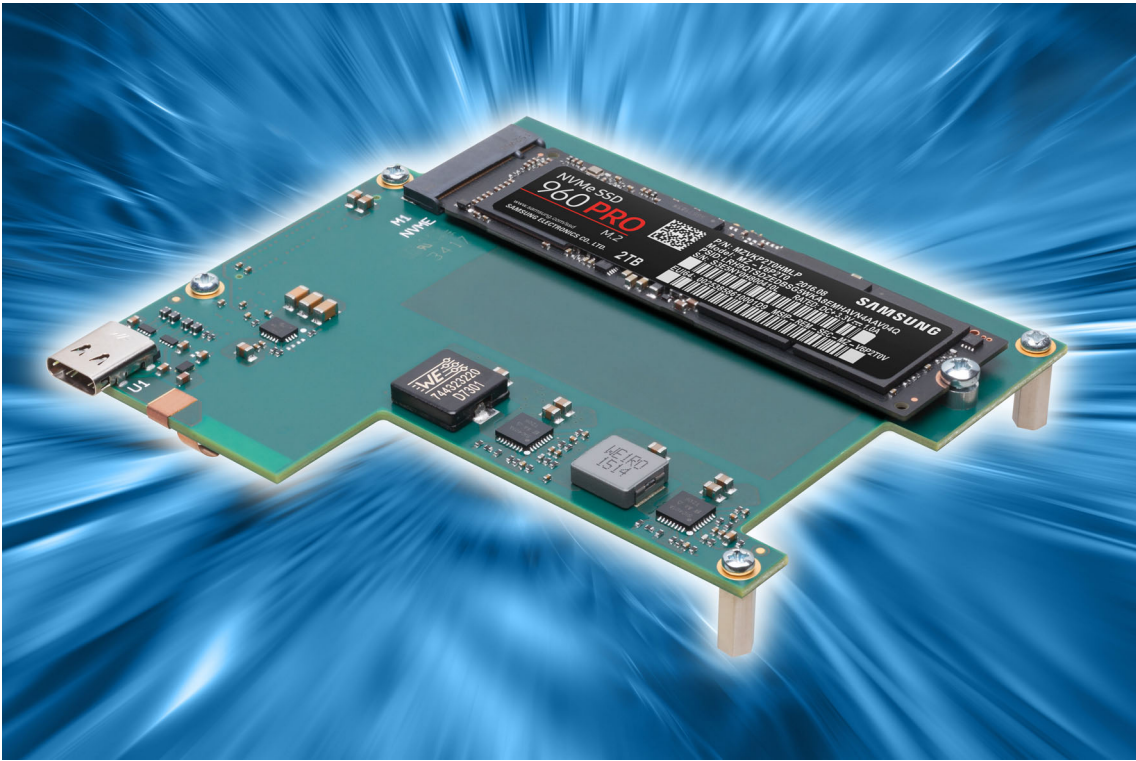
The connectors HSE1 and HSE2 are high speed connectors, as required for PCI Express® Gen4 and USB3 10Gbps. The socket EXP is used as a legacy interface (e.g. HD Audio, UART) and not required for many mezzanine modules. All mezzanine connectors allow board-to-board heights of 10.0mm (S20, S40, S48), 10.8mm (S80, S82), and 18.7mm (e.g. SCJ, SCL side cards 8HP assembly).

HSE1 is assigned to a PCIe® Gen4 x4 link, derived directly from the CPU. On a 4HP low profile mezzanine module or 8HP side card this link is wired to a fast Gen3 or Gen4 NVMe SSD housed in an M.2 socket, typically used as boot device and general mass storage. In addition, HSE1 brings a 10Gbps USB3 port, often used for front I/O.

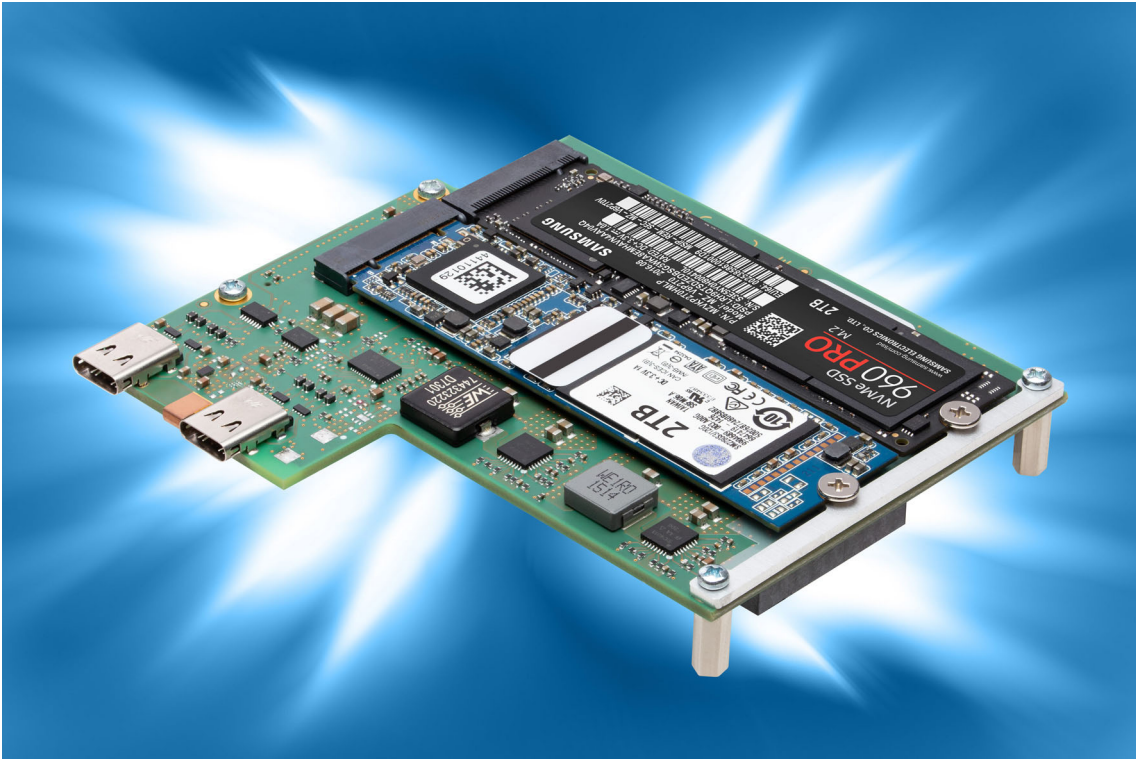
HSE2 provides another four PCIe® Gen3 lanes, configurable for versatile link width and combinations, and in addition a 4th DisplayPort video output. Some mezzanine modules such as the S20 get along with the HSE1 connector alone, others such as S40, S48 or S80 depend on both HSE1 and HSE2 for full functionality.

Related Information Mezzanine Connectors

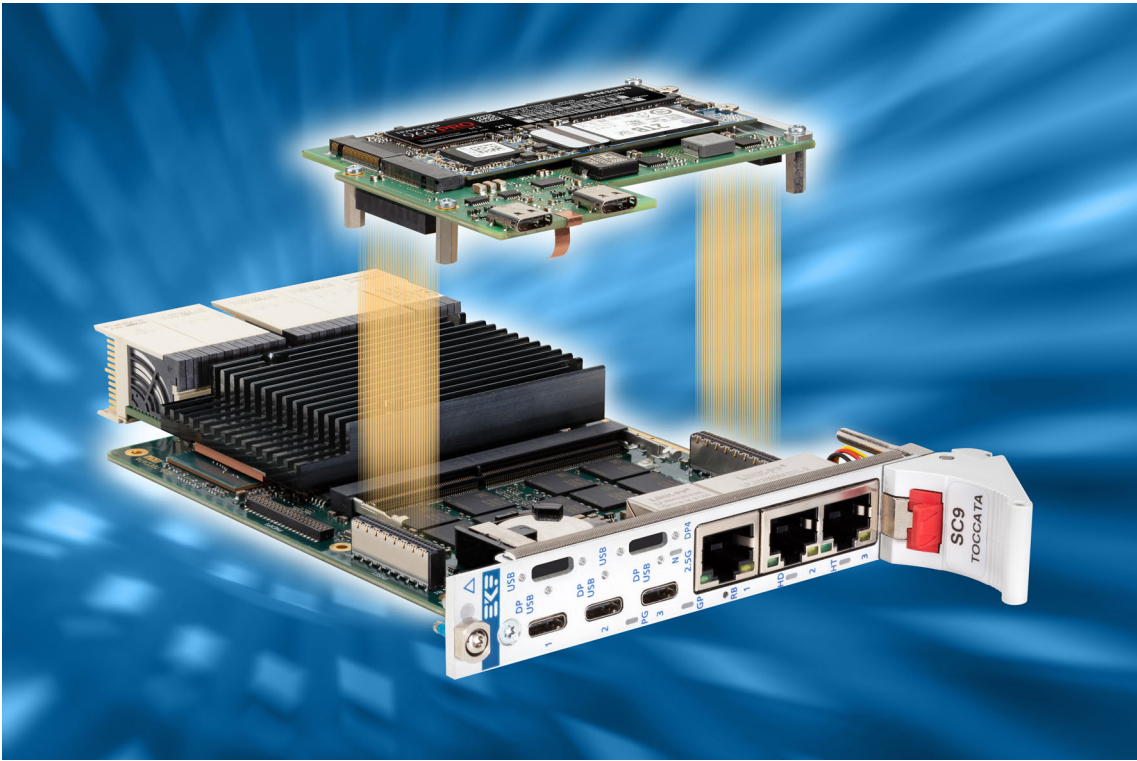
https://www.ekf.com/s/mezzanine_connectors.pdf



S20-NVME Low Profile Mezzanine Module



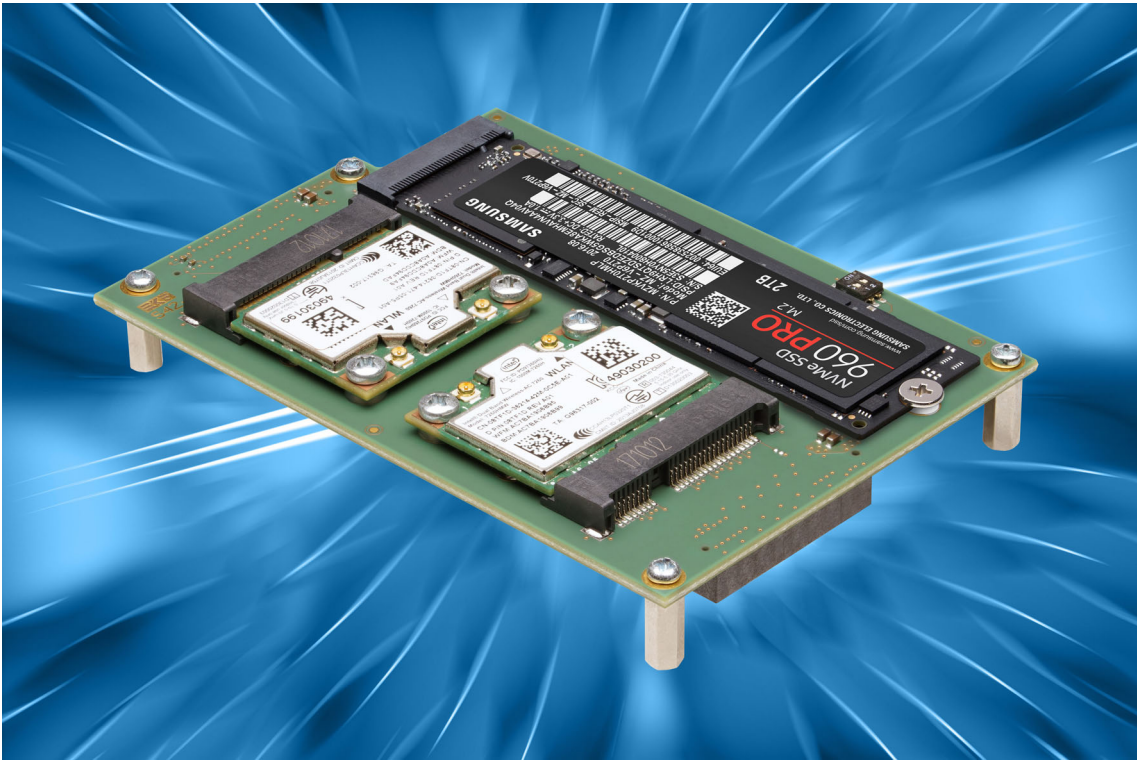
S40-NVME Low Profile Mezzanine Module



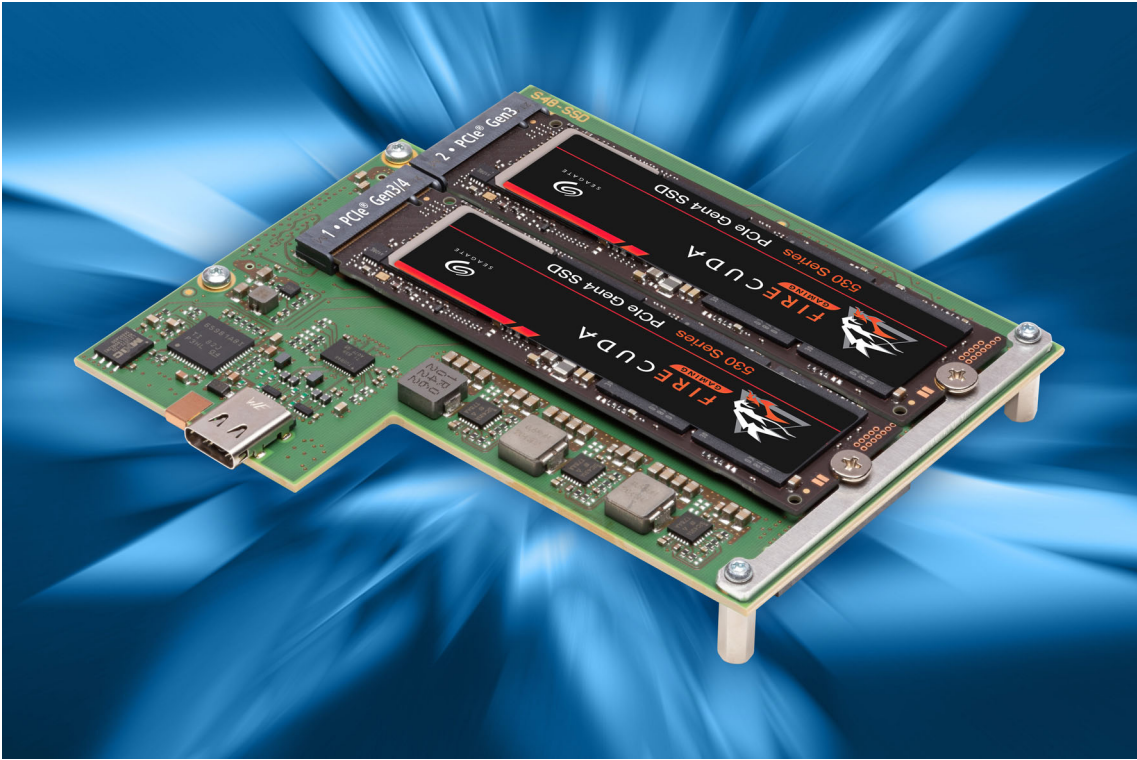
SC9 w. S40



SC9 w. S40



S42-MC Low Profile Mezzanine Module



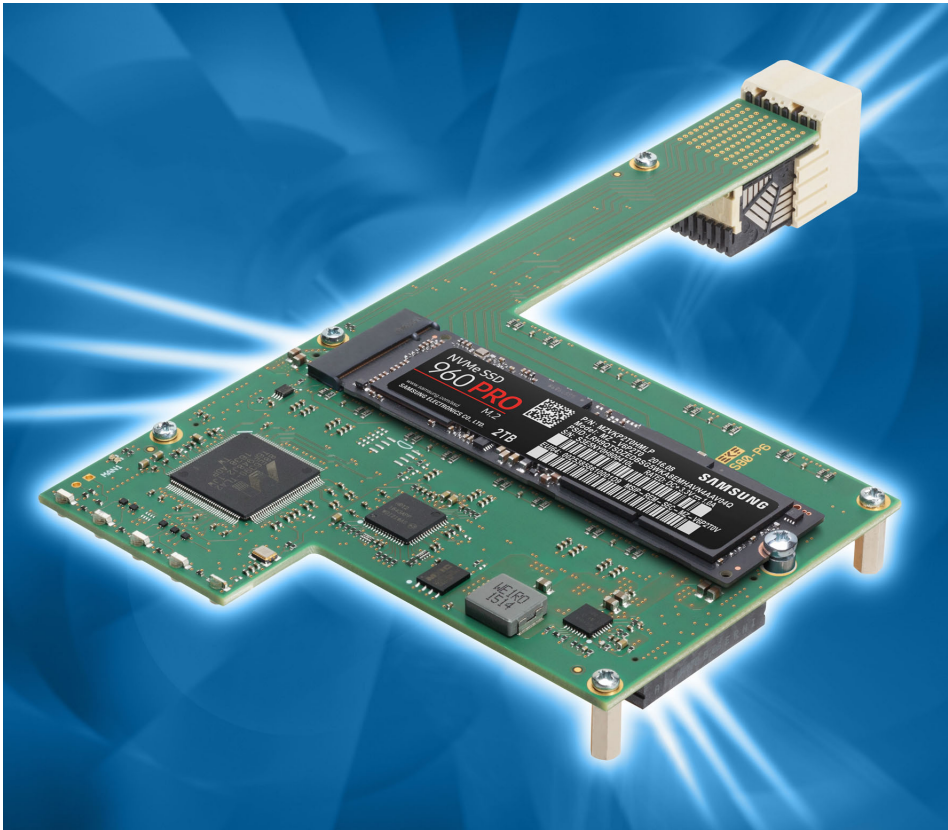
S48-SSD Low Profile Mezzanine Module



SC9 w. S48



SC9 w. S48



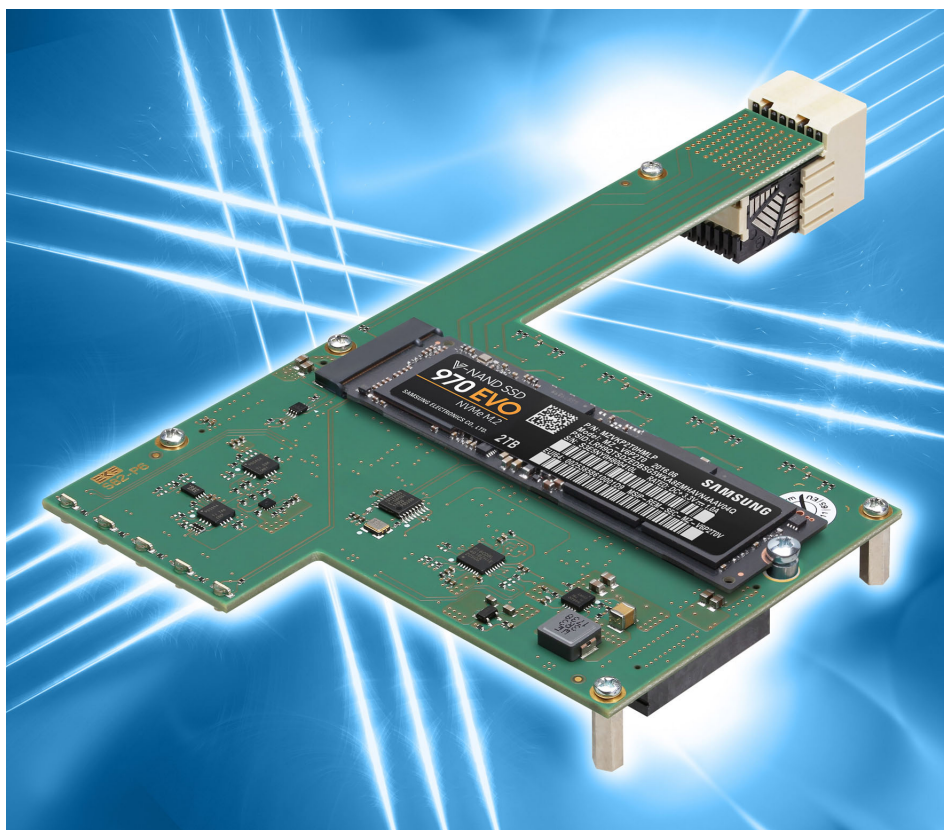
S80-P6 Low Profile Mezzanine Module



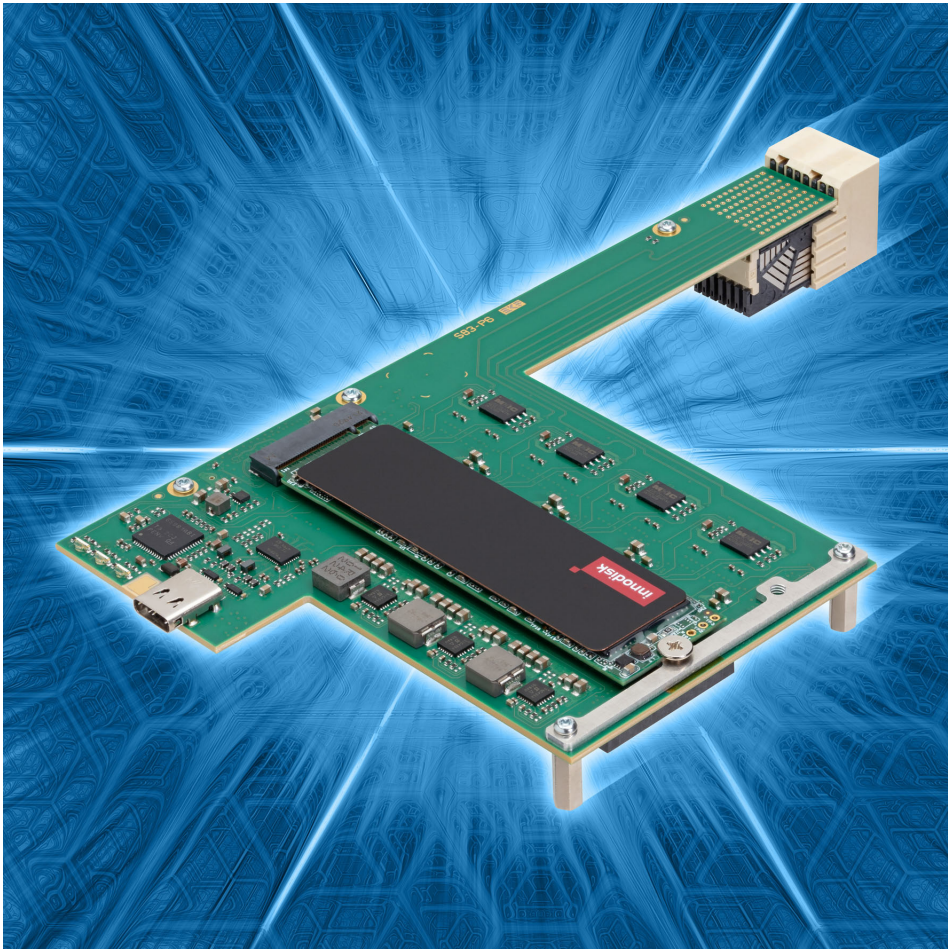
SC9 w. S80



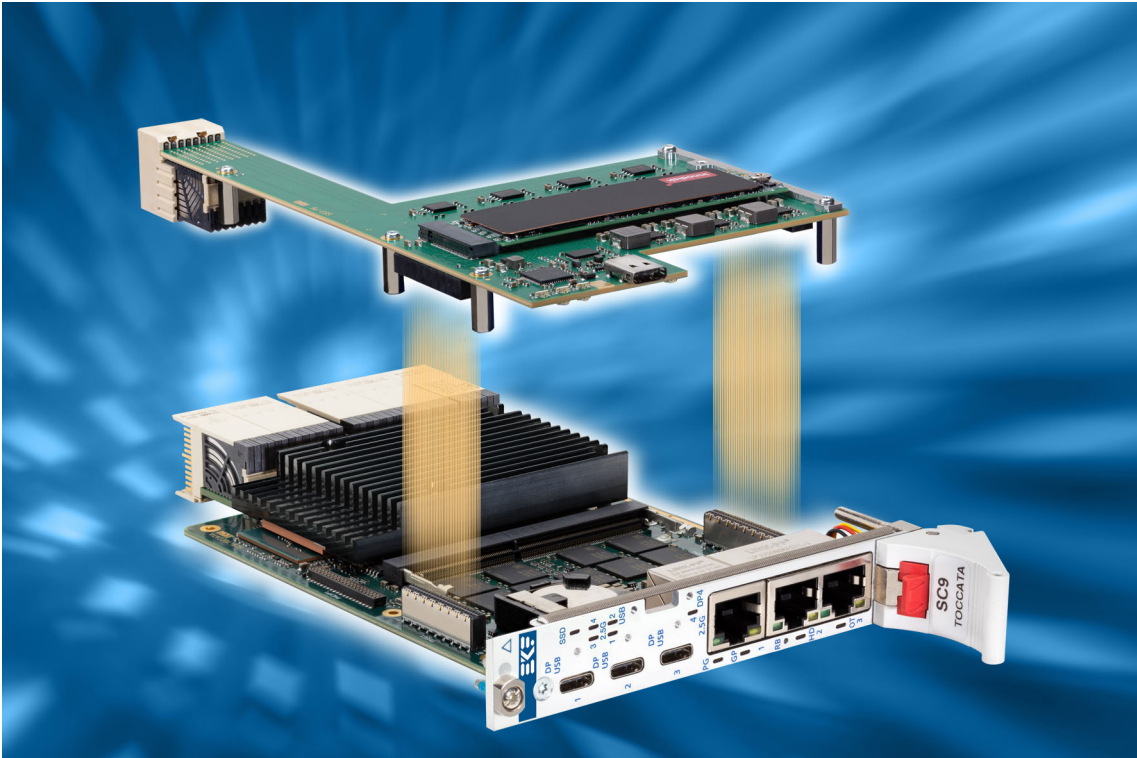
SC9 w. S80



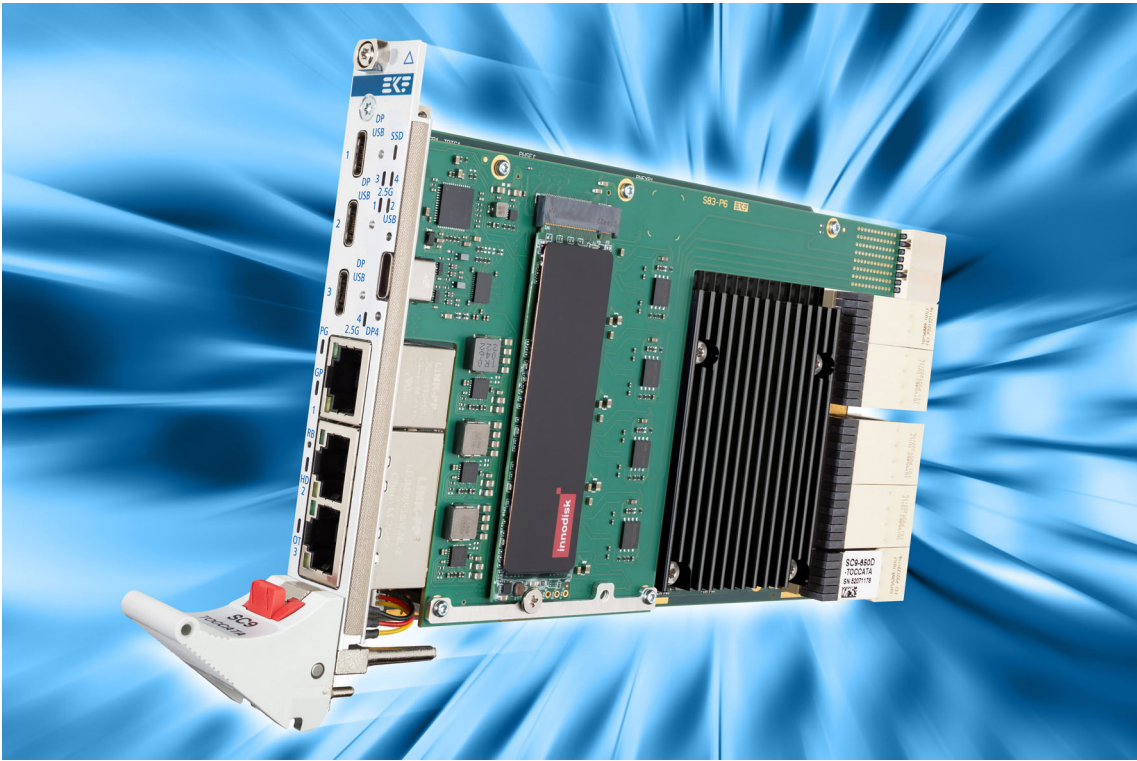
S82-P6 Low Profile Mezzanine Module



S83-P6 Low Profile Mezzanine Module



SC9 w. S83



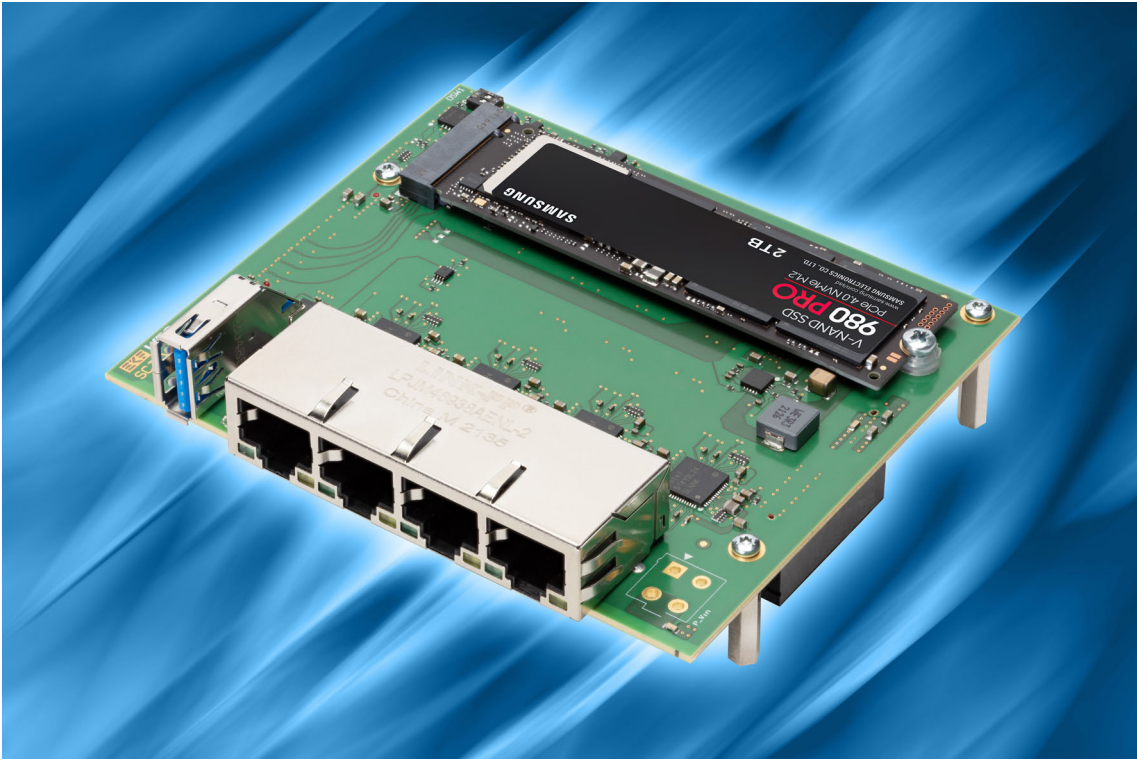
SC9 w. S83



SC9 w. S83



SC9 w. SCJ-VEENA 8HP Assembly



SCJ-VEENA Side Card

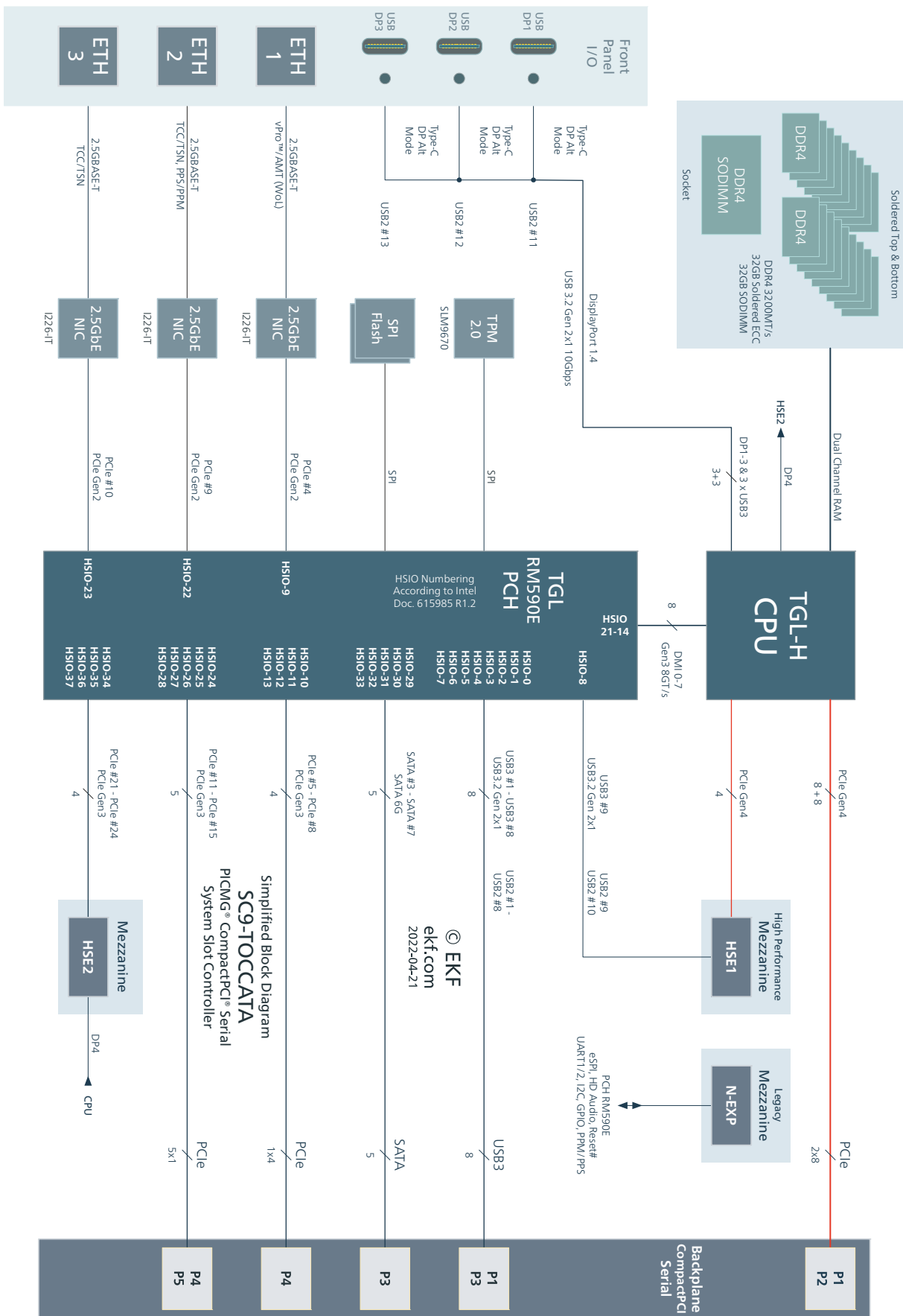


SC9 w. SCL-RHYTHM 8HP Assembly



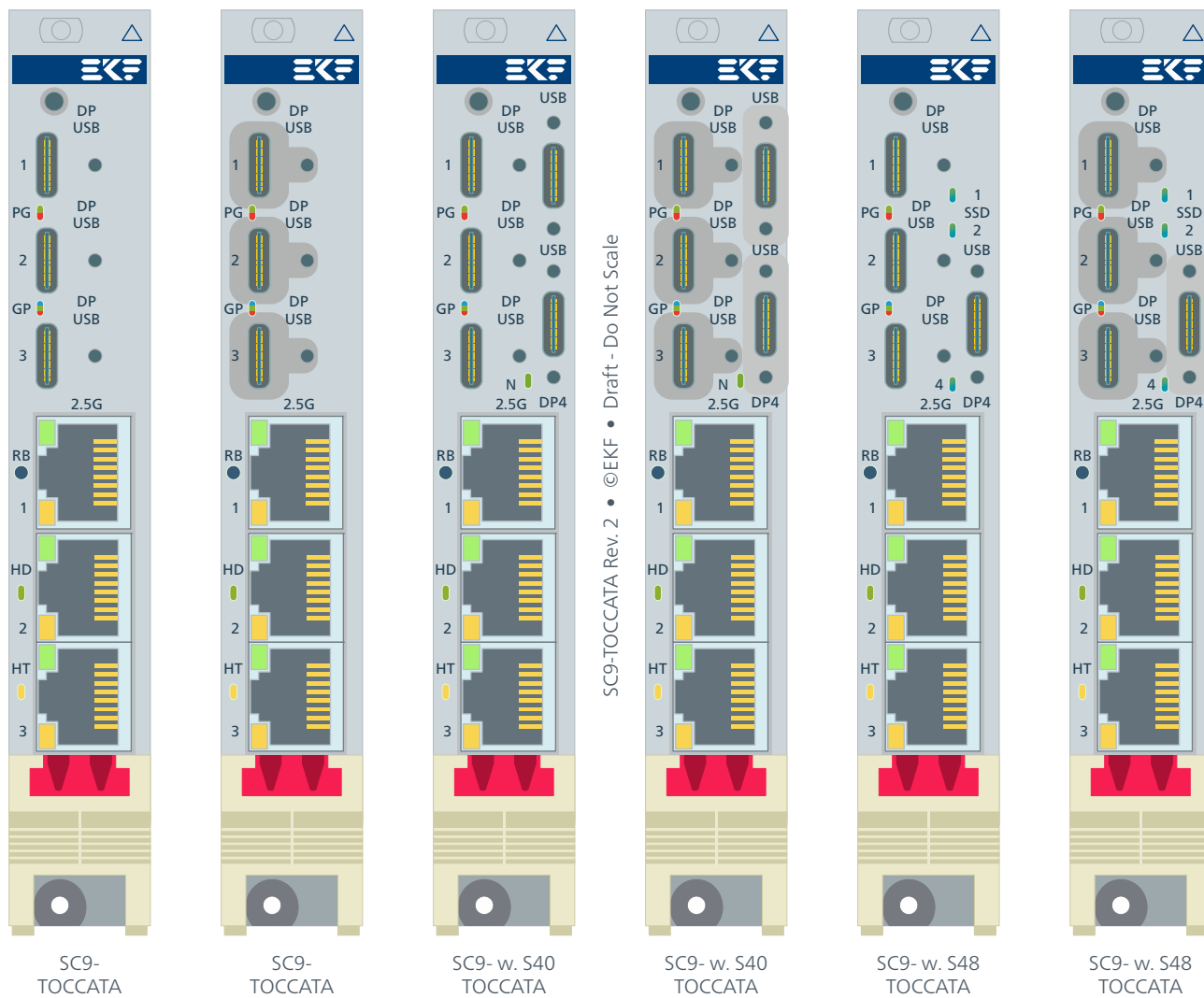
SC9 w. SCZ-NVM 8HP/12HP Assembly

Block Diagram

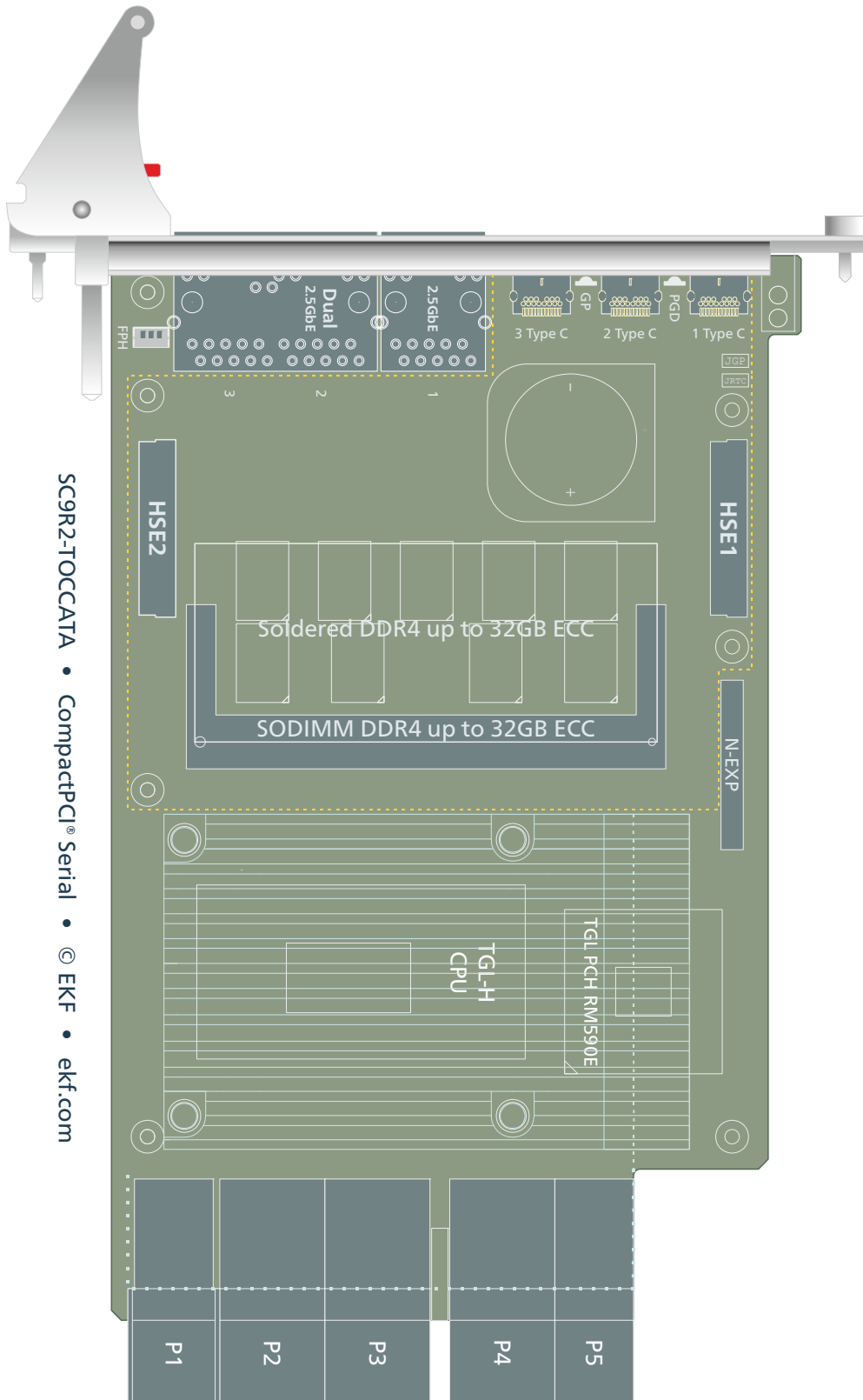


https://www.ekf.com/s/sc9/img/sc9_blk.pdf

Front Panel



Component Orientation



SC9R2-TOCCATA • CompactPCI® Serial • © EKF • ekf.com

Backplane Resources

SC9-TOCCATA • Resources w. 1+8 Slots Backplane (System Slot Left Aligned Version)

Slot	Resources	Slot	Resources	Slot	Resources	Slot	Resources	Slot	Resources	Slot	Resources	Slot	Resources						
P6	1 SYS GbE*** (1-8) Clk PE (1-8) PE Gen3 x1 (7-8) PE Gen3 x1 (4-6) PE Gen3 x4 (3)	P5	2 GbE*** (1) GA 111 PER 1 CPU TGL-H	P4	3 GbE*** (2) GA 110 PER 2 CPU TGL-H	P3	4 GbE*** (3) GA 101 PER 3 PCH RM590E HSIO 10-13 PCIe #5-8	P2	5 GbE*** (4) GA 100 PER 4 PCH RM590E HSIO 24 PCIe #11	P1	6 GbE*** (5) GA 011 PER 5 PCH RM590E HSIO 25 PCIe #12	7	GbE*** (6) GA 010 PER 6 PCH RM590E HSIO 26 PCIe #13	8	GbE*** (7) GA 001 PER 7 PCH RM590E HSIO 27 PCIe #14	9	GbE*** (8) GA 000 PER 8 PCH RM590E HSIO 28 PCIe #15		
													Peripheral Slot						

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system slot connector assignment numbers in brackets e.g. SATA (4-8) according to the CPCI-5.0 specification table 44/45

* PCIe® Gen4 not specified by CPCI-5.0 R2.0 - subject to PICMG® working group
 ** USB3.2 Gen2x1 (10G) not specified by CPCI-5.0 R2.0 - subject to PICMG® working group
 *** P6 Gigabit Ethernet requires e.g. 580/582 low profile mezzanine module

SC9-TOCCATA • Resources w. 1+8 Slots Backplane (System Slot Right Aligned Version)

	①	②	③	④	⑤	⑥	⑦	⑧	⑨ SYS
P6	GbE*** (8)	GbE*** (7)	GbE*** (6)	GbE*** (5)	GbE*** (4)	GbE*** (3)	GbE*** (2)	GbE*** (1)	GbE*** (1-8)
P5	GA 000	GA 001	GA 010	GA 011	GA 100	GA 101	GA 110	GA 111	CLK PE (1-8) PE Gen3 x1 (7-8)
P4	PER 8	PER 7	PER 6	PER 5	PER 4	PER 3	PER 2	PER 1	PE Gen3 x1 (4-6) PE Gen3 x4 (3)
P3	PCH RM590E HSIO 28 PCIe #15	PCH RM590E HSIO 27 PCIe #14	PCH RM590E HSIO 26 PCIe #13	PCH RM590E HSIO 25 PCIe #12	PCH RM590E HSIO 24 PCIe #11	PCH RM590E HSIO 10-13 PCIe #5-8	CPU TGL-H	CPU TGL-H	SATA (4-8) USB3.2** (2-8)
P2									PE Gen4* x8 (2) ½ PE Gen4* x8 (1)
P1	PE Gen3 x1 SATA USB3.2**	PE Gen3 x1 SATA USB3.2**	PE Gen3 x1 SATA USB3.2**	PE Gen3 x1 SATA USB3.2**	PE Gen3 x1 SATA USB3.2**	PE Gen3 x4 USB3.2**	PE Gen4* x8 USB3.2**	PE Gen4* x8 USB3.2**	½ PE Gen4* x8 (1) USB3.2** (1)
	Peripheral Slot	Peripheral Slot	Peripheral Slot	Peripheral Slot	Peripheral Slot	Peripheral Slot	Fat Pipe Slot	Fat Pipe Slot	SC9- TOCCATA

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system slot connector assignment numbers in brackets e.g. SATA (4-8) according to the CPCI-S.0 specification table 44/45

* PCIe® Gen4 not specified by CPCI-S.0 R2.0 - subject to PICMG® working group

** USB3.2 Gen2x1 (10G) not specified by CPCI-S.0 R2.0 - subject to PICMG® working group

*** P6 Gigabit Ethernet requires e.g. S80/S82 low profile mezzanine module

Related Information	
SC9-TOCCATA Home	https://www.ekf.com/s/sc9/sc9.html
S20-NVME Low Profile Mezzanine	https://www.ekf.com/s/s20/s20.html
S40-NVME Low Profile Mezzanine	https://www.ekf.com/s/s40/s40.html
S42-MC Low Profile Mezzanine	https://www.ekf.com/s/s42/s42.html
S48-SSD Low Profile Mezzanine	https://www.ekf.com/s/s48/s48.html
S80-P6 Low Profile Mezzanine	https://www.ekf.com/s/s80/s80.html
S82-P6 Low Profile Mezzanine	https://www.ekf.com/s/s82/s82.html
S83-P6 Low Profile Mezzanine	https://www.ekf.com/s/s83/s83.html
<i>S84-P6 Low Profile Mezzanine</i>	<i>1 x 10G Backplane Ethernet (KR)</i>
<i>S85-P6 Low Profile Mezzanine</i>	<i>4 x 5G Backplane Ethernet (5GBASE-T)</i>
<i>SCG-MULTIGIG Mezzanine Side Card</i>	<i>2 x 10GBASE-T M12-X</i>
<i>SCI-MULTIGIG Mezzanine Side Card</i>	<i>2 x 10GBASE-T RJ45</i>
SCJ-VEENA Mezzanine Side Card	https://www.ekf.com/s/scj/scj.html
SCL-RHYTHM Mezzanine Side Card	https://www.ekf.com/s/scl/scl.html
SCX-PCIE Mezzanine Side Card	https://www.ekf.com/s/scx/scx.html
SCZ-NVM Mezzanine Side Card	https://www.ekf.com/s/scz/scz.html
ECX-PCIE Mezzanine Side Card	https://www.ekf.com/e/ecx/ecx.html
Mezzanine Connectors Explained	https://www.ekf.com/s/mezzanine_connectors.pdf

General Information CompactPCI® Serial	
CompactPCI® Serial Concise Overview	https://www.ekf.com/s/serial_concise.pdf
CompactPCI® Serial All You Need to Know	https://www.ekf.com/s/smart_solution.pdf
CompactPCI® Serial Home	https://www.ekf.com/s/serial.html

Ordering Information
For popular SC9-TOCCATA SKUs please refer to https://www.ekf.com/liste/liste_21.html#SC9
For new mezzanine connector based low profile modules please refer to https://www.ekf.com/liste/liste_21.html#S20

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